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(54) Title: SLURRY COMPOSITION FOR SECONDARY POLISHING OF SILICON WAFER

(57) Abstract: Disclosed is a slurry composition for secondary polishing of silicon wafers comprising: 2 ~ 10 weight% of colloidal silica having an average particle size of 30 ~ 80 nm; 0.5 ~ 1.5 % by weight of ammonia; 0.2 ~ 1 weight% of a hydroxyalkylcellulose-based polymer for modifying rheology of the composition; 0.03 ~ 0.5 weight% of a polyoxyethylenealkylamine ether-based nonionic surfactant; 0.01 ~ 1 weight% of a quaternary ammonium base and the balance of deionized water.

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